

Washpoint *Washing Station*



The Washpoint is a self-contained, fully integrated free standing washing station for cleaning and drying wafers, substrate or plates up to 150mm with added capability for wafers up to 300mm in diameter following dicing, scribing or other machining processes.

A flexible washing process allows all elements of the cleaning and drying sequence; cycle time, water pressure, gas pressure and dry heat output to be easily adjusted to meet individual process demands while the compact case ensures maximum use of work areas.

FEATURES:

Easy to operate / maintain
High pressure water jet
Fully programmable
Centrifugal spin off
Safety switches & interlocks

Hot air dryer temperature controlled.
Dry air or nitrogen drying gas
Automatic or manual operation
Detergent injection

CLEANING AND DRYING PROCESS

The versatile washing process is adaptable to both volume production and research and development environments. An automatic mode follows a programmed wash and dry sequence to ensure improved production throughput, while a manual mode allows independent control of all elements of the process.

The washing cycle uses filtered high pressure water supplied by a powerful air driven pump to clean the component, and water may be de-ionised or contain additives depending on application. The drying sequence directs a dry air or nitrogen jet across the component surface to clear the water particles. An inline heater warms the drying gas and component to enhance the effectiveness of the drying process. An integral mist extraction unit draws off spray and vapour to provide a superior cleaning environment. Cleaning area enclosed by shutter that opens and closes automatically.



Water, detergent
drying gas feed

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Washpoint 300 v5



Wash programmes are entered via touch sensitive screen.
The shutter door is interlocked to washing sequence
System is designed for automation

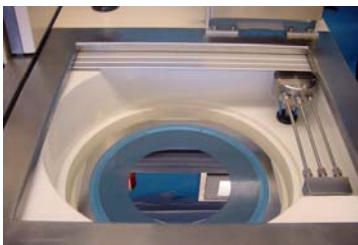


SPECIFICATION

- Construction - Painted stainless steel
- Programming - Via touch sensitive screen and PLCC unit
- Capacity - Up to 300mm, 12" diameter wafers, discs or plates.
- Chuck - Vacuum diameter 300mm vacuum standard
- Optional - Mechanical chuck to suit wide range of ring frames
- Spin speed - 0 – 2000 rpm
- Water jet - 0 – 140 bar (3000psi) by air driven pump, depending on jet.
- Gas jet - 0 – 5.5 bar, dry air or nitrogen
- Heater - Hot air or gas heater in line
- Regulators - Air/nitrogen pressure, water pressure
- Interlocks - Air/nitrogen, Water and Vacuum pressure.
- Safety interlocks and stops as defined by CE standard requirements

SUPPLIES

- Electricity - 220/240v AC single phase 6A, 50/60Hz
- Dry air or - 5.5 bar @ 0.085 cu.m/min, nitrogen diameter 8mm nylon pipe
- Compressed air - 5.5 bar @ 0.085 cu.m /min diameter 8mm pipe to pump
- DI water - 2.0 bar @ 2.0 l/min, 12mm dia. pipe
- Vacuum - 500mm Hg continuous, with water trap, 12mm dia. pipe
- Mist extraction - Integral mist extractor and vapour trap, 50 mm vent
- Drain - Free open drain, not less than 300mm below outlet
- Size - 520 x 520 x 800 mm (w x d x h)
- Weight - 150 Kilograms



200 mm silicon wafer cleaning



300 mm glass disc cleaning



Multiple tape ring cleaning

The information on the Washpoint is provisional and subject to amendment.

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